



9M 2835

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re the Application of:

Fung Leng Chen, et al.

Serial No.: 09/115,444

Filed: 07/14/98

For: High Density Internal Ball Grid Array Integrated Circuit Package

Docket No.: TIS-25912

Examiner: Not Assigned

Art Unit: 2835 #5/IDS

E. Millio

6-9-99

INFORMATION DISCLOSURE STATEMENT

Assistant Commission for Patents

Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(a)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner of Patents, Washington, D.C. 20231.

  
Tina Rendon

11-12-98  
Date

Applicants wish to bring the references noted on the enclosed PTO-1449 to the attention of the Patent and Trademark Office. The enclosed articles and/or patents listed on the attached PTO 1449 form are deemed relevant to the above-referenced application.

Please charge any additional fees to deposit account 20-0668.

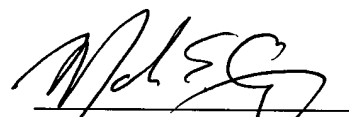
Texas Instruments Incorporated  
P. O. Box 655474, M/S 3999  
Dallas, Texas 75265  
(972) 917-5632  
Fax: (972) 917-4418

RECEIVED

NOV 19 1998

GROUP 2100

Respectfully submitted,

  
Mark E. Courtney  
Reg. No. 36,491